



Material Content Data Sheet



Sales Product Name		SAK-XC164CS-32F40F BB-A		Issued		29. August 2013		
MA#		MA000971540						
Package		PG-TQFP-100-5		Weight*		699.69 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	33.010	4.72	4.72	47177	47177
leadframe	non noble metal	magnesium	7439-95-4	0.282	0.04		403	
	inorganic material	silicon	7440-21-3	1.222	0.17		1746	
	non noble metal	nickel	7440-02-0	5.638	0.81		8058	
wire	non noble metal	copper	7440-50-8	180.785	25.84	26.86	258378	268585
	noble metal	gold	7440-57-5	2.953	0.42	0.42	4221	4221
encapsulation	organic material	carbon black	1333-86-4	2.300	0.33		3288	
	plastics	epoxy resin	-	62.107	8.88		88763	
	inorganic material	silicondioxide	60676-86-0	395.643	56.54	65.75	565453	657504
leadfinish	non noble metal	tin	7440-31-5	6.201	0.89	0.89	8862	8862
plating	noble metal	silver	7440-22-4	3.477	0.50	0.50	4970	4970
glue	plastics	epoxy resin	-	1.215	0.17		1736	
	noble metal	silver	7440-22-4	4.859	0.69	0.86	6945	8681
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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